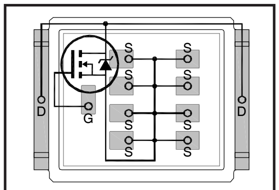
Automotive DirectFET® Power MOSFET ②

- Advanced Process Technology
- Optimized for Automotive Motor Drive, DC-DC and other Heavy Load Applications
- Exceptionally Small Footprint and Low Profile
- High Power Density
- Low Parasitic Parameters
- Dual Sided Cooling
- 175°C Operating Temperature
- Repetitive Avalanche Capability for Robustness and Reliability
- Lead Free, RoHS Compliant and Halogen Free
- Automotive Qualified *

$V_{(BR)DSS}$		100V
$R_{DS(on)}$	typ.	2.8mΩ
	max.	3.5mΩ
$I_{D\ (Silicon\ Limited)}$		124A
Q_g		200nC



L8

DirectFET® ISOMETRIC

Applicable DirectFET® Outline and Substrate Outline ①

SB	SC			M2	M4		L4	L6	L8	

Description

The AUIRF7769L2TR combines the latest Automotive HEXFET® Power MOSFET Silicon technology with the advanced DirectFET® packaging to achieve the lowest on-state resistance in a package that has the footprint of a DPak (TO-252AA) and only 0.7 mm profile. The DirectFET® package is compatible with existing layout geometries used in power applications, PCB assembly equipment and vapor phase, infra-red or convection soldering techniques, when application note AN-1035 is followed regarding the manufacturing methods and processes. The DirectFET® package allows dual sided cooling to maximize thermal transfer in automotive power systems.

This HEXFET® Power MOSFET is designed for applications where efficiency and power density are essential. The advanced DirectFET® packaging platform coupled with the latest silicon technology allows the AUIRF7769L2TR to offer substantial system level savings and performance improvement specifically in motor drive, high frequency DC-DC and other heavy load applications on ICE, HEV and EV platforms. This MOSFET utilizes the latest processing techniques to achieve low on-resistance and low Qg per silicon area. Additional features of this MOSFET are 175°C operating junction temperature and high repetitive peak current capability. These features combine to make this MOSFET a highly efficient, robust and reliable device for high current automotive applications.

Ordering Information

Base part number	Package Type	Standard Pack		Complete Part Number
		Form	Quantity	
AUIRF7769L2	DirectFET2 Large Can	Tape and Reel	4000	AUIRF7769L2TR

Absolute Maximum Ratings

Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied.Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T_A) is 25°C, unless otherwise specified.

	Parameter	Max.	Units
V_{DS}	Drain-to-Source Voltage	100	V
V_{GS}	Gate-to-Source Voltage	±20	
I_D @ T_C = 25°C	Continuous Drain Current, V_{GS} @ 10V (Silicon Limited)④	124	A
I_D @ T_C = 100°C	Continuous Drain Current, V_{GS} @ 10V (Silicon Limited)④	88	
I_D @ T_A = 25°C	Continuous Drain Current, V_{GS} @ 10V (Silicon Limited)③	20	
I_D @ T_C = 25°C	Continuous Drain Current, V_{GS} @ 10V (Package Limited)	375	
I_{DM}	Pulsed Drain Current ⑤	500	
P_D @T_C = 25°C	Power Dissipation ④	125	W
P_D @T_A = 25°C	Power Dissipation ③	3.3	
E_{AS}	Single Pulse Avalanche Energy ⑥	260	mJ
I_{AR}	Avalanche Current ⑤	See Fig.18a, 18b, 16, 17	A
E_{AR}	Repetitive Avalanche Energy ⑤		mJ
T_P	Peak Soldering Temperature	270	°C
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to + 175	

HEXFET® is a registered trademark of International Rectifier.
*Qualification standards can be found at http://www.irf.com/

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient ③	—	45	°C/W
$R_{\theta JA}$	Junction-to-Ambient ⑧	12.5	—	
$R_{\theta JA}$	Junction-to-Ambient ⑨	20	—	
$R_{\theta J\text{-}can}$	Junction-to-Can ④⑩	—	1.2	
$R_{\theta J\text{-}PCB}$	Junction-to-PCB Mounted	—	0.5	
	Linear Derating Factor ④	0.83		W/°C

Static Characteristics @ T_J = 25°C (unless otherwise stated)

	Parameter	Min.	Typ.	Max.	Units	Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	100	—	—	V	V_{GS} = 0V, I_D = 250μA
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.02	—	V/°C	Reference to 25°C, I_D = 2mA
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	2.8	3.5	mΩ	V_{GS} = 10V, I_D = 74A ⑦
$V_{GS(th)}$	Gate Threshold Voltage	2.0	2.7	4.0	V	V_{DS} = V_{GS}, I_D = 250μA
$\Delta V_{GS(th)}/\Delta T_J$	Gate Threshold Voltage Coefficient	—	-10	—	mV/°C	
gfs	Forward Transconductance	410	—	—	S	V_{DS} = 25V, I_D = 74A
I_{DSS}	Drain-to-Source Leakage Current	—	—	20	μA	V_{DS} = 100V, V_{GS} = 0V
		—	—	250		V_{DS} = 80V, V_{GS} = 0V, T_J = 125°C
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	V_{GS} = 20V
	Gate-to-Source Reverse Leakage	—	—	-100		V_{GS} = -20V

Dynamic Characteristics @ T_J = 25°C (unless otherwise stated)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge	—	200	300	nC	
Q_{gs1}	Pre-Vth Gate-to-Source Charge	—	30	—		V_{DS} = 50V
Q_{gs2}	Post-Vth Gate-to-Source Charge	—	9.0	—		V_{GS} = 10V
Q_{gd}	Gate-to-Drain Charge	—	110	165		I_D = 74A
Q_{godr}	Gate Charge Overdrive	—	51	—		See Fig. 9
Q_{sw}	Switch Charge (Q_{gs2} + Q_{gd})	—	119	—		
Q_{oss}	Output Charge	—	53	—	nC	V_{DS} = 16V, V_{GS} = 0V
R_G	Gate Resistance	—	1.5	—	Ω	
$t_{d(on)}$	Turn-On Delay Time	—	44	—	ns	V_{DD} = 50V, V_{GS} = 10V ⑦
t_r	Rise Time	—	32	—		I_D = 74A
$t_{d(off)}$	Turn-Off Delay Time	—	92	—		R_G=1.8Ω
t_f	Fall Time	—	41	—		
C_{iss}	Input Capacitance	—	11560	—	pF	V_{GS} = 0V
C_{oss}	Output Capacitance	—	1240	—		V_{DS} = 25V
C_{rss}	Reverse Transfer Capacitance	—	590	—		f = 1.0MHz
C_{oss}	Output Capacitance	—	6665	—		V_{GS} = 0V, V_{DS} = 1.0V, f=1.0MHz
C_{oss}	Output Capacitance	—	690	—		V_{GS} = 0V, V_{DS} = 80V, f=1.0MHz

Diode Characteristics @ T_J = 25°C (unless otherwise stated)

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	124	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ⑤	—	—	500		
V_{SD}	Diode Forward Voltage	—	—	1.3	V	T_J = 25°C, I_S = 74A, V_{GS} = 0V ⑦
t_{rr}	Reverse Recovery Time	—	75	112	ns	T_J = 25°C, I_F = 74A, V_{DD} = 50V
Q_{rr}	Reverse Recovery Charge	—	220	330	nC	di/dt = 100A/μs ⑦

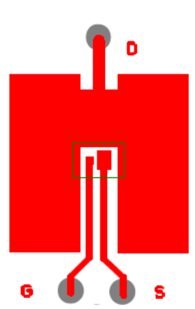
Qualification Information†

Qualification Level		Automotive (per AEC-Q101) ††	
		Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.	
Moisture Sensitivity Level		LARGE-CAN	MSL1
ESD	Machine Model	Class M4 (+/- 800V)††† (per AEC-Q101-002)	
	Human Body Model	Class H3A (+/- 6000V)††† (per AEC-Q101-001)	
	Charged Device Model	N/A (per AEC-Q101-005)	
RoHS Compliant		Yes	

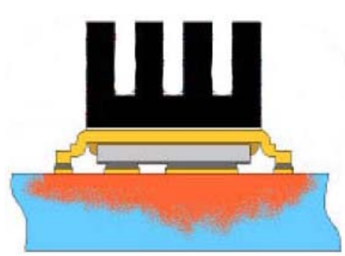
† Qualification standards can be found at International Rectifier's web site: http//www.irf.com/

†† Exceptions (if any) to AEC-Q101 requirements are noted in the qualification report.

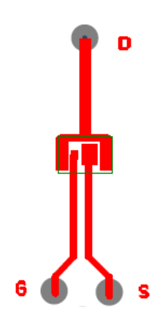
††† Highest passing voltage



③ Surface mounted on 1 in. square Cu (still air).



⑨ Mounted to a PCB with small clip heatsink (still air)



⑨ Mounted on minimum footprint full size board with metalized back and with small clip heatsink (still air)

Notes ① through ⑩ are on page 10

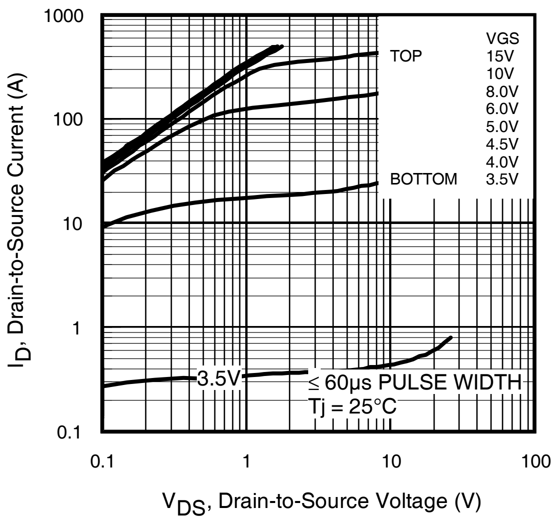


Fig 1. Typical Output Characteristics

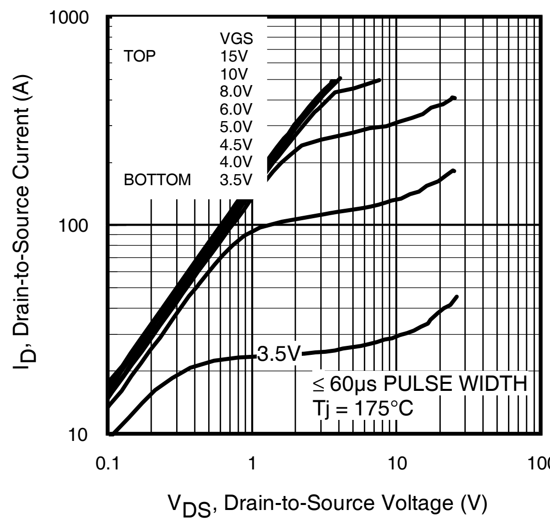


Fig 2. Typical Output Characteristics

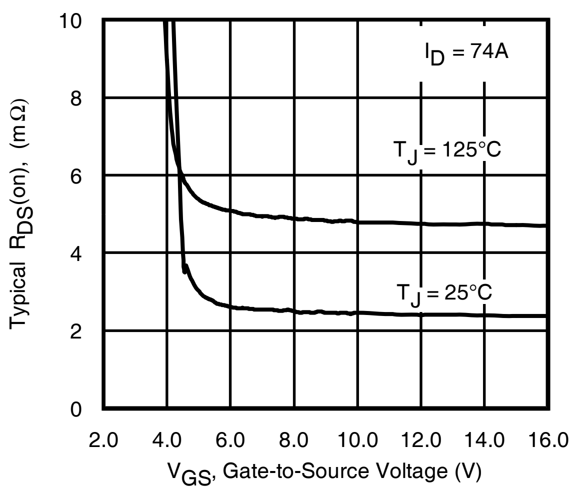


Fig 3. Typical On-Resistance vs. Gate Voltage

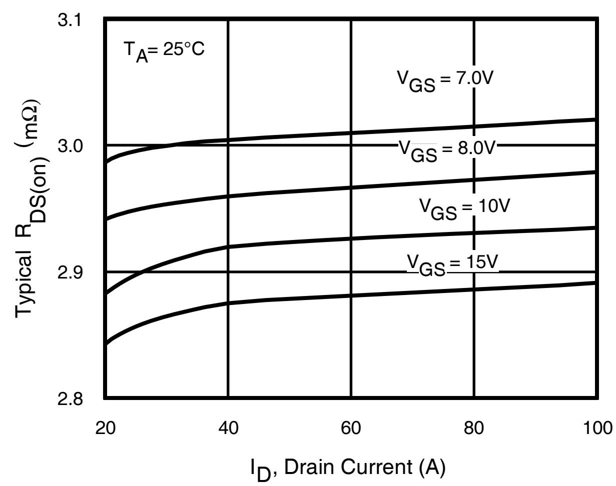


Fig 4. Typical On-Resistance vs. Drain Current

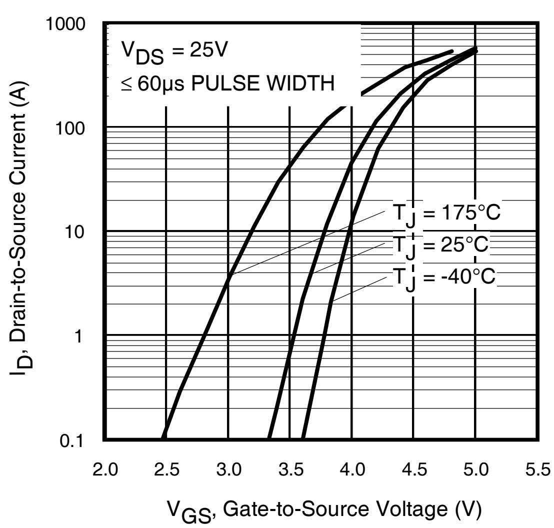


Fig 5. Typical Transfer Characteristics

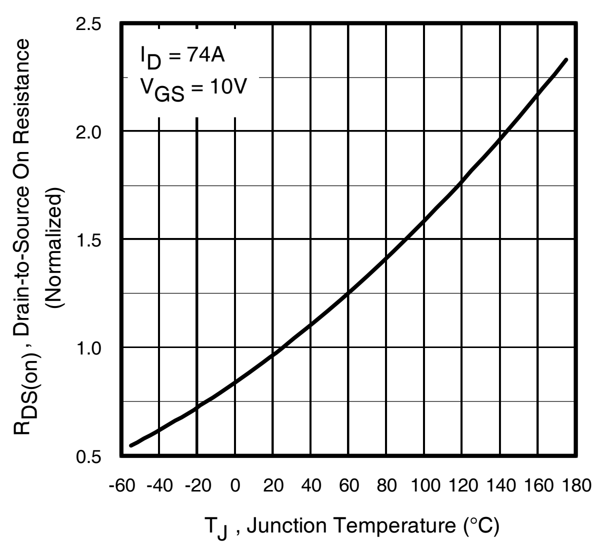


Fig 6. Normalized On-Resistance vs. Temperature

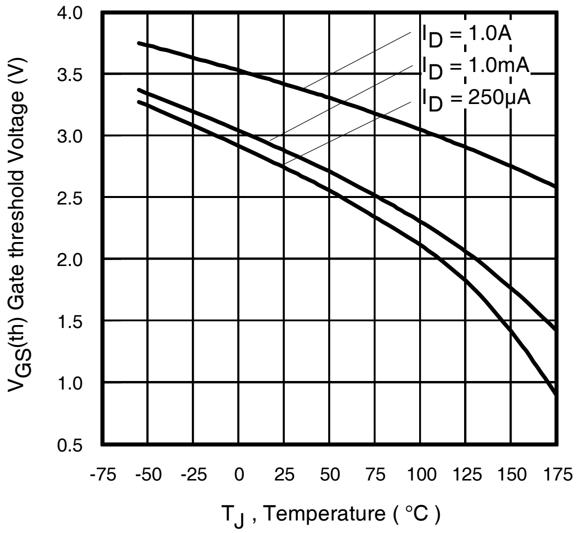


Fig 7. Typical Threshold Voltage vs. Junction Temperature

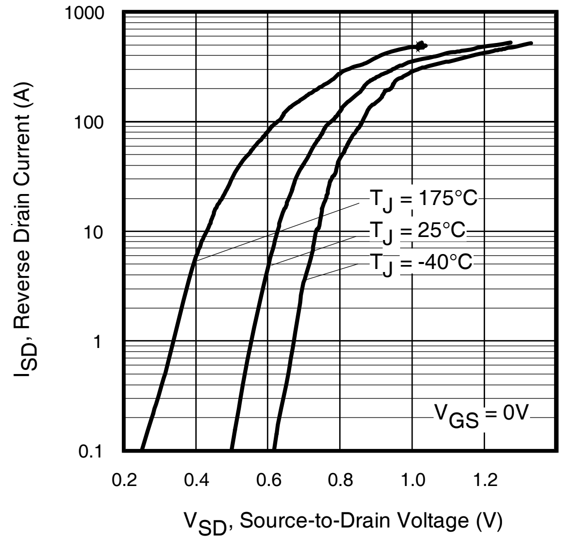


Fig 8. Typical Source-Drain Diode Forward Voltage

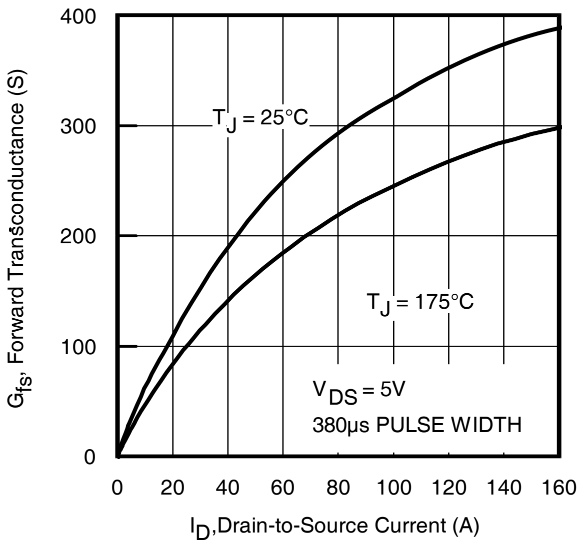


Fig 9. Typical Forward Transconductance vs. Drain Current

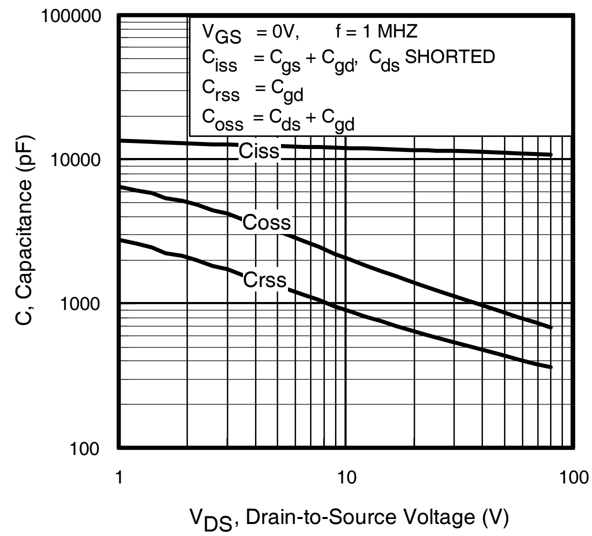


Fig 10. Typical Capacitance vs.Drain-to-Source Voltage

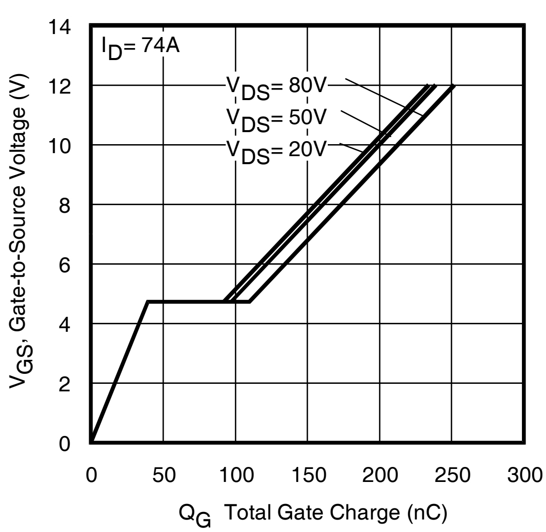


Fig.11 Typical Gate Charge vs.Gate-to-Source Voltage

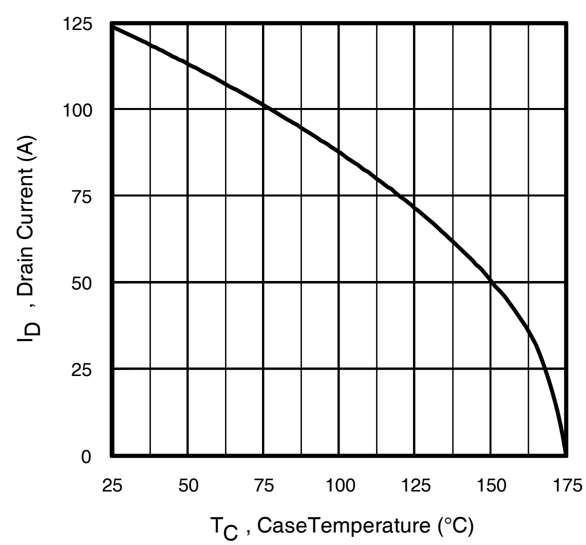


Fig 12. Maximum Drain Current vs. Case Temperature

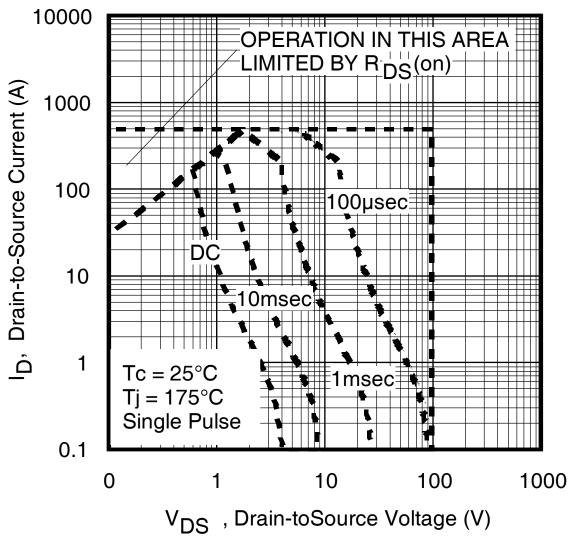


Fig 13. Maximum Safe Operating Area

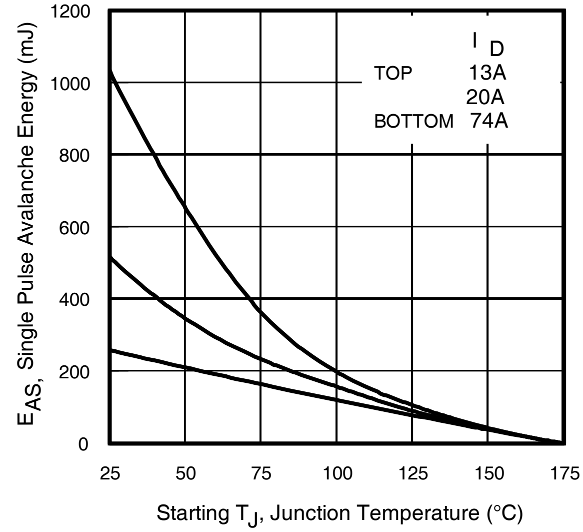
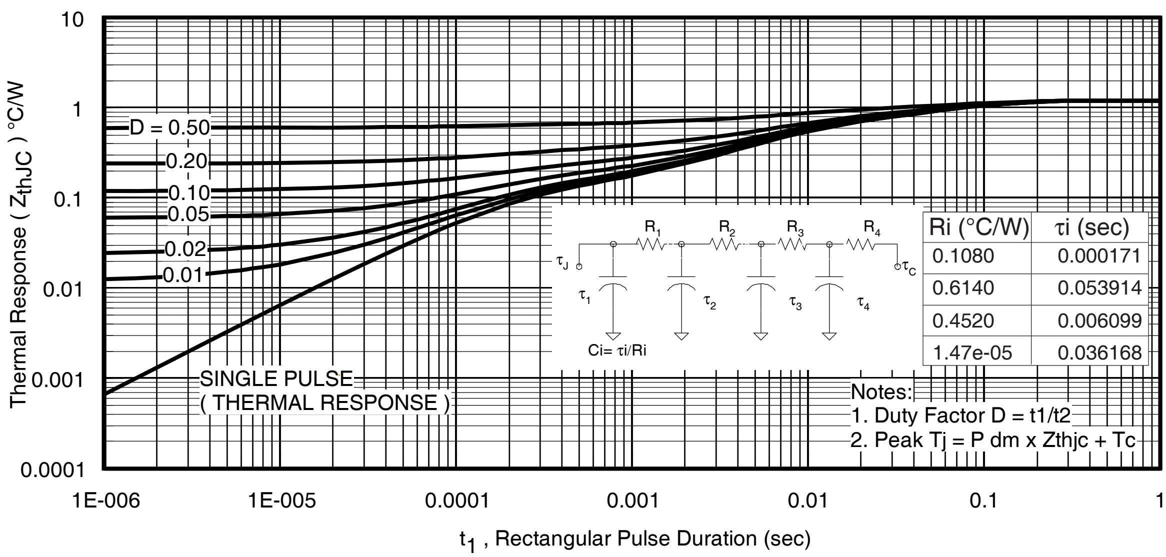


Fig 14. Maximum Avalanche Energy vs. Temperature



Ri (°C/W)	τi (sec)
0.1080	0.000171
0.6140	0.053914
0.4520	0.006099
1.47e-05	0.036168

Fig 15. Maximum Effective Transient Thermal Impedance, Junction-to-Case

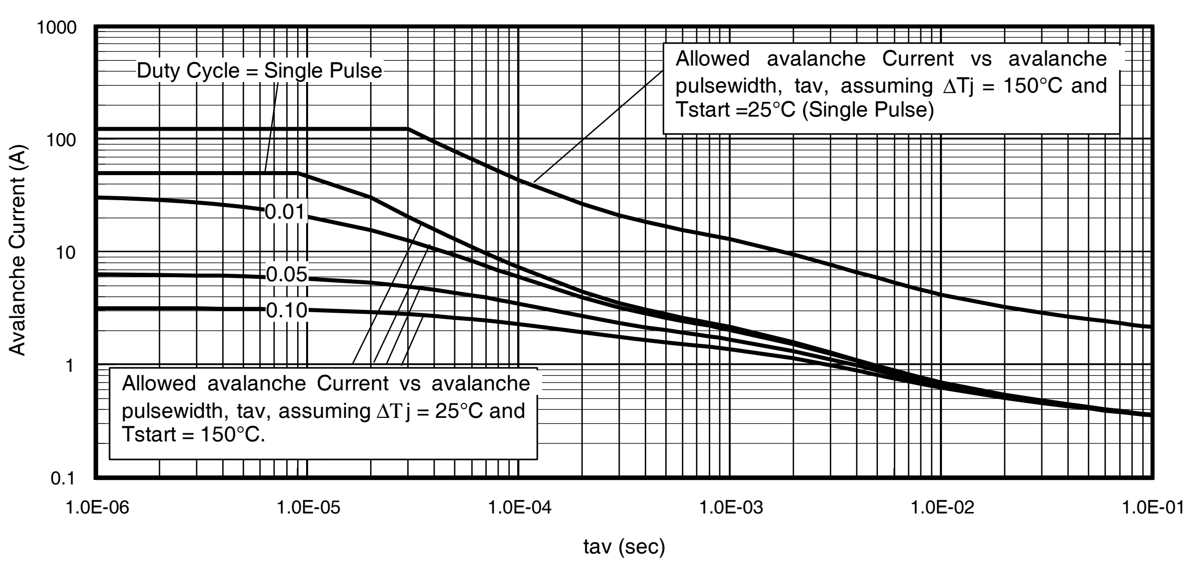


Fig 16. Typical Avalanche Current vs.Pulsewidth

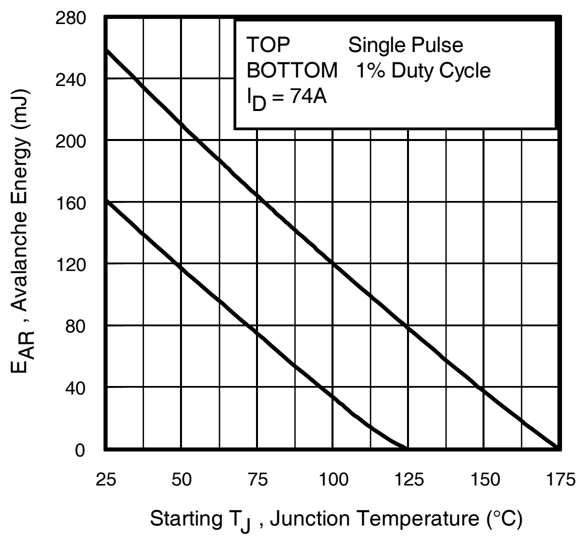


Fig 17. Maximum Avalanche Energy vs. Temperature

Notes on Repetitive Avalanche Curves , Figures 13, 14:
(For further info, see AN-1005 at www.irf.com)

1. Avalanche failures assumption:
   Purely a thermal phenomenon and failure occurs at a temperature far in excess of T_{jmax}. This is validated for every part type.
2. Safe operation in Avalanche is allowed as long asT_{jmax} is not exceeded.
3. Equation below based on circuit and waveforms shown in Figures 16a, 16b.
4. $P_{D\ (ave)}$ = Average power dissipation per single avalanche pulse.
5. BV = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
6. I_{av} = Allowable avalanche current.
7. ΔT = Allowable rise in junction temperature, not to exceed T_{jmax} (assumed as 25°C in Figure 15, 16).
   t_{av} = Average time in avalanche.
   D = Duty cycle in avalanche = $t_{av} \cdot f$
   $Z_{thJC}(D, t_{av})$ = Transient thermal resistance, see figure 11)

$$P_{D\ (ave)} = 1/2\ (1.3 \cdot BV \cdot I_{av}) = \Delta T / Z_{thJC}$$
$$I_{av} = 2\Delta T / [1.3 \cdot BV \cdot Z_{th}]$$
$$E_{AS\ (AR)} = P_{D\ (ave)} \cdot t_{av}$$

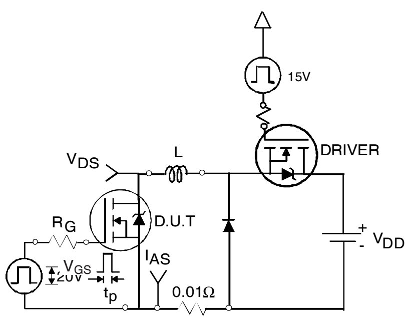


Fig 18a. Unclamped Inductive Test Circuit

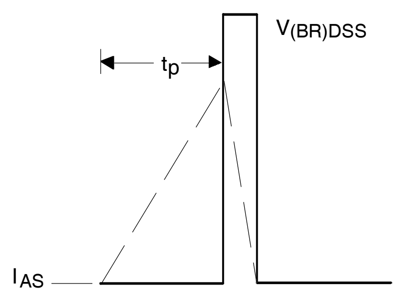


Fig 18b. Unclamped Inductive Waveforms

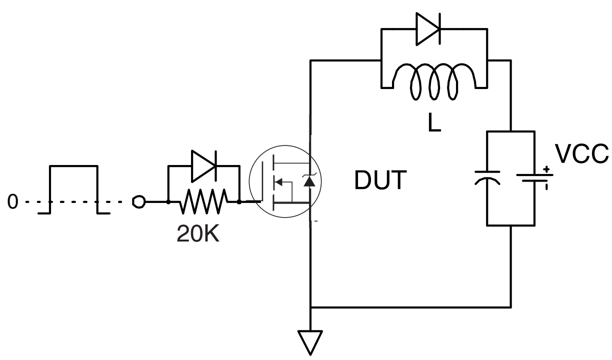


Fig 19a. Gate Charge Test Circuit

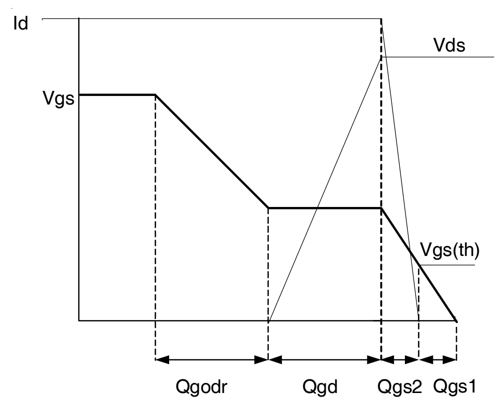


Fig 19b. Gate Charge Waveform

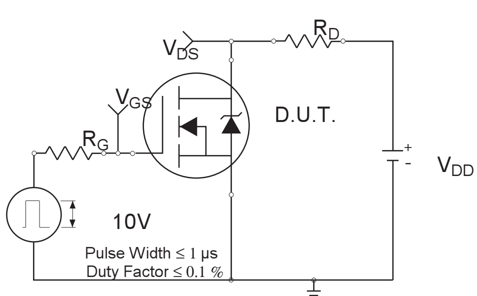


Fig 20a. Switching Time Test Circuit

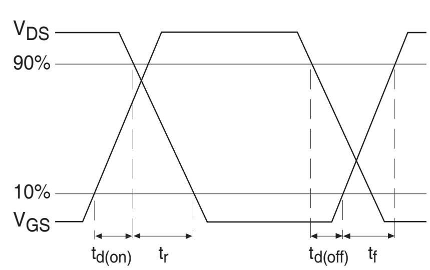
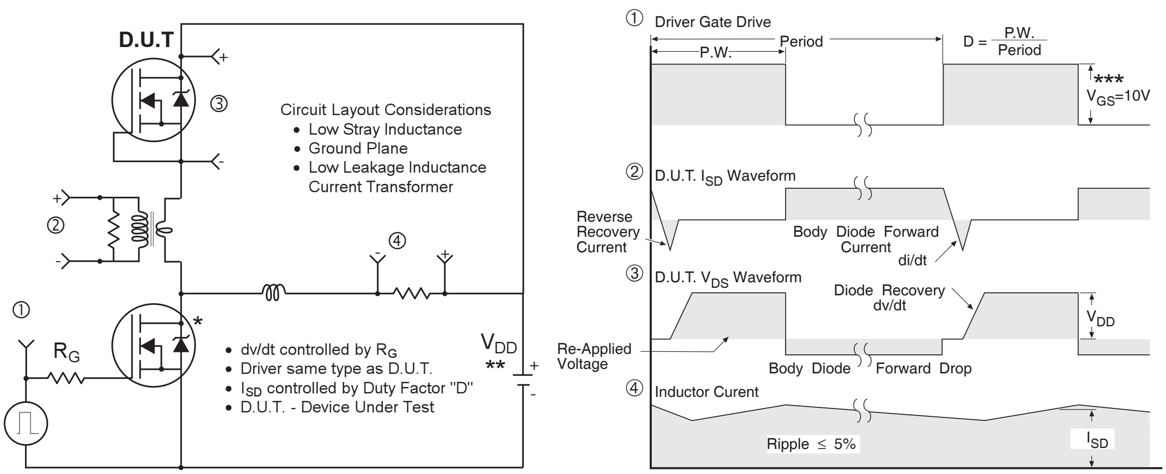


Fig 20b. Switching Time Waveforms



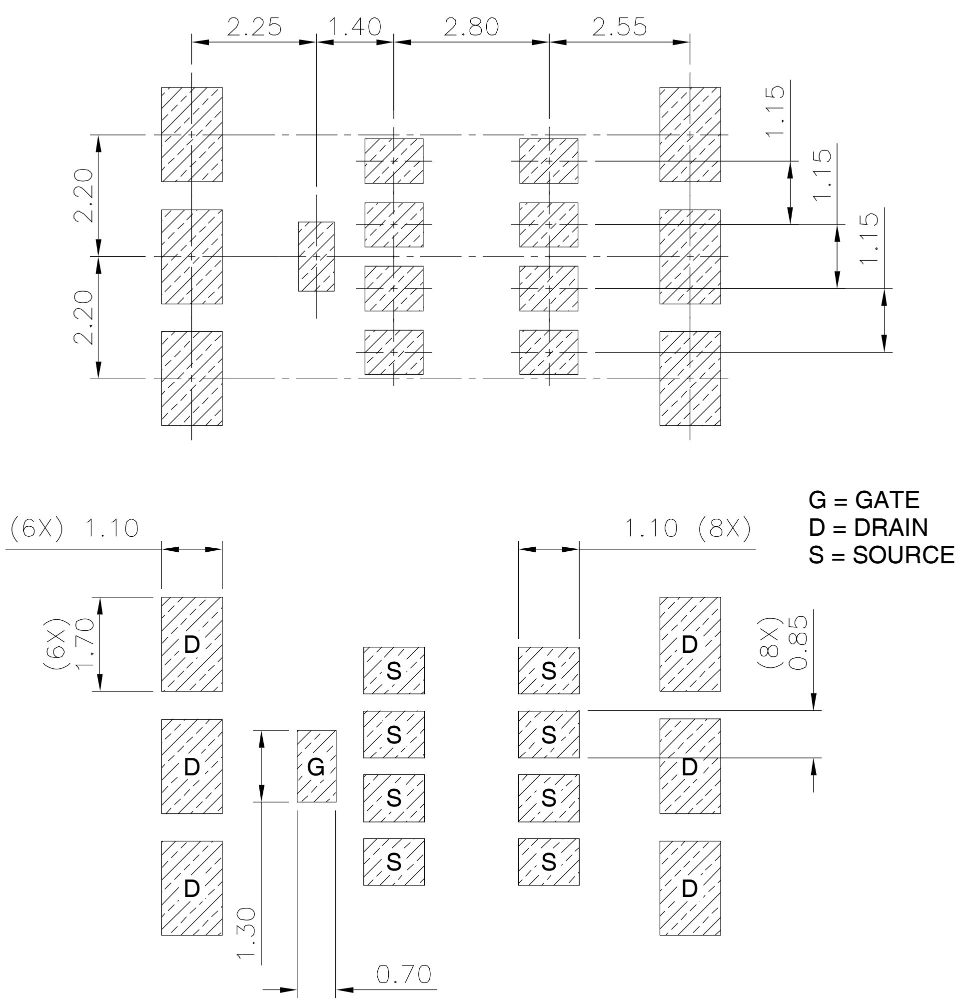
* Use P-Channel Driver for P-Channel Measurements
** Reverse Polarity for P-Channel

*** V_{GS} = 5V for Logic Level Devices

Fig 21. Diode Reverse Recovery Test Circuit for HEXFET® Power MOSFETs

Automotive DirectFET® Board Footprint, L8 (Large Size Can).

Please see AN-1035 for DirectFET® assembly details and stencil and substrate design recommendations

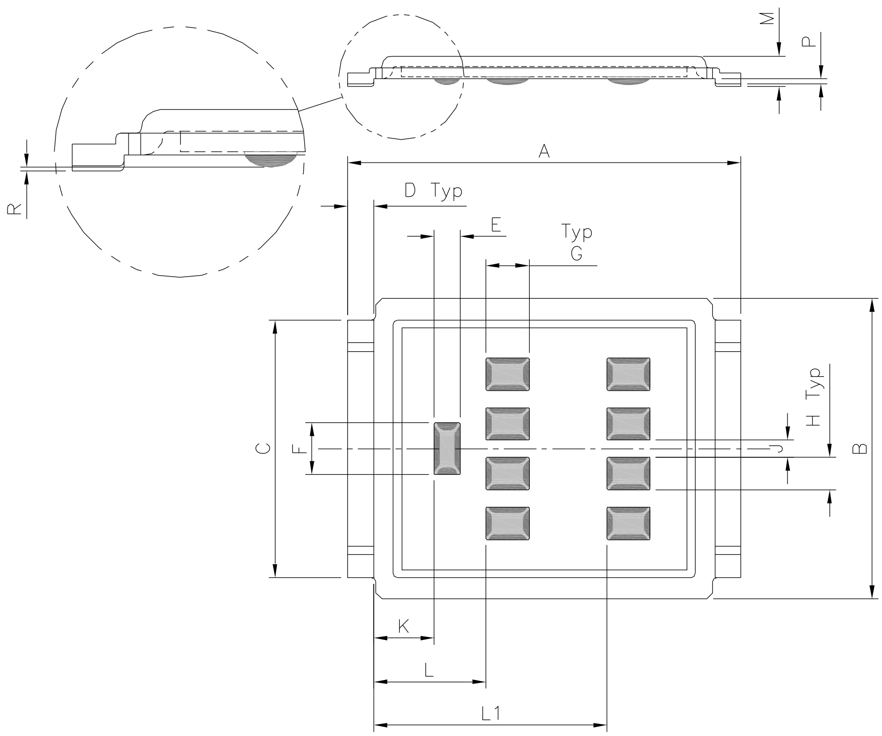


G = GATE
D = DRAIN
S = SOURCE

Note: For the most current drawing please refer to IR website at http://www.irf.com/package

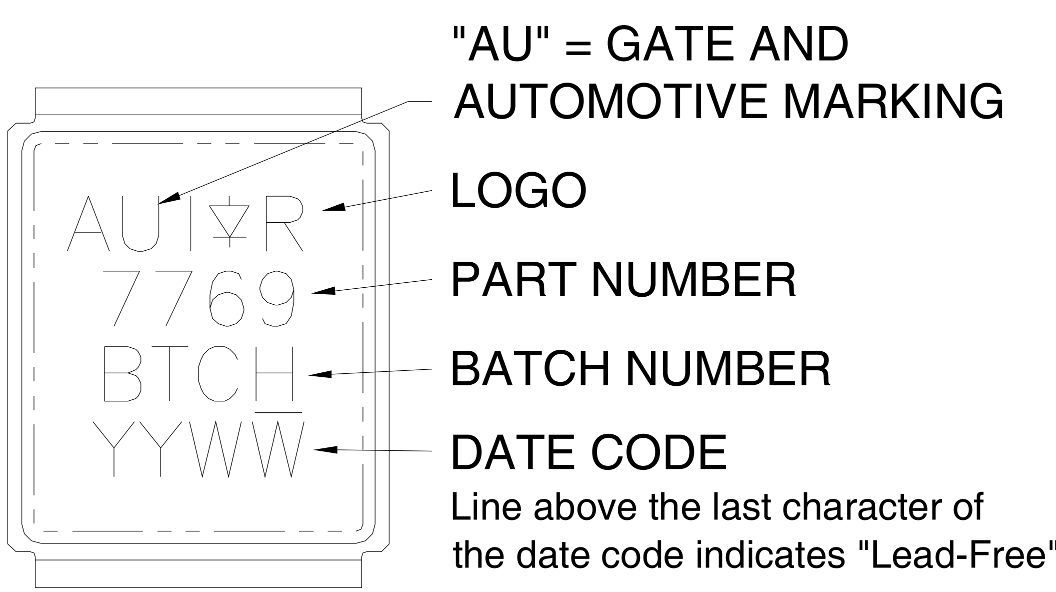
Automotive DirectFET® Outline Dimension, L8 Outline (LargeSize Can).

Please see AN-1035 for DirectFET® assembly details and stencil and substrate design recommendations



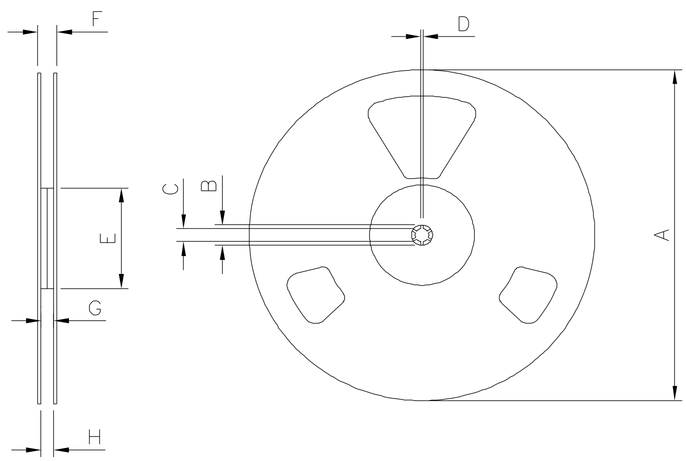
DIMENSIONS				
	METRIC		IMPERIAL	
CODE	MIN	MAX	MIN	MAX
A	9.05	9.15	0.356	0.360
B	6.85	7.10	0.270	0.280
C	5.90	6.00	0.232	0.236
D	0.55	0.65	0.022	0.026
E	0.58	0.62	0.023	0.024
F	1.18	1.22	0.046	0.048
G	0.98	1.02	0.039	0.040
H	0.73	0.77	0.029	0.030
J	0.38	0.42	0.015	0.017
K	1.35	1.45	0.053	0.057
L	2.55	2.65	0.100	0.104
L1	5.35	5.45	0.211	0.215
M	0.68	0.74	0.027	0.029
P	0.09	0.17	0.003	0.007
R	0.02	0.08	0.001	0.003

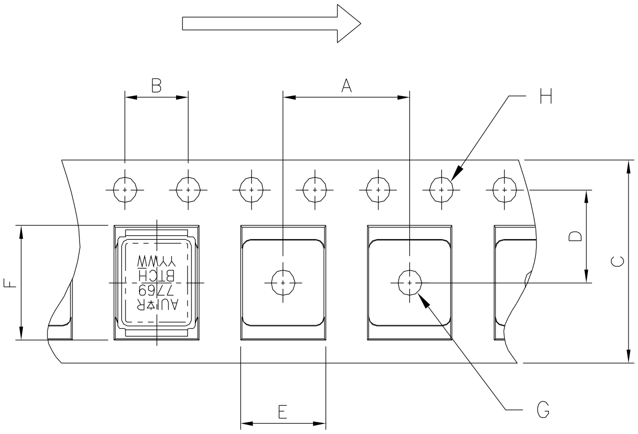
Automotive DirectFET® Part Marking



Note: For the most current drawing please refer to IR website at http://www.irf.com/package

Automotive DirectFET® Tape & Reel Dimension (Showing component orientation).





NOTE: Controlling dimensions in mm
Std reel quantity is 4000 parts. (ordered as AUIRF7769L2TR).

REEL DIMENSIONS				
STANDARD OPTION **(QTY 4000)**				
	METRIC		IMPERIAL	
CODE	MIN	MAX	MIN	MAX
A	330.00	N.C	12.992	N.C
B	20.20	N.C	0.795	N.C
C	12.80	13.20	0.504	0.520
D	1.50	N.C	0.059	N.C
E	99.00	100.00	3.900	3.940
F	N.C	22.40	N.C	0.880
G	16.40	18.40	0.650	0.720
H	15.90	19.40	0.630	0.760

NOTE: CONTROLLING DIMENSIONS IN MM

DIMENSIONS				
	METRIC		IMPERIAL	
CODE	MIN	MAX	MIN	MAX
A	11.90	12.10	4.69	0.476
B	3.90	4.10	0.154	0.161
C	15.90	16.30	0.623	0.642
D	7.40	7.60	0.291	0.299
E	7.20	7.40	0.283	0.291
F	9.90	10.10	0.390	0.398
G	1.50	N.C	0.059	N.C
H	1.50	1.60	0.059	0.063

Note: For the most current drawing please refer to IR website at http://www.irf.com/package

Notes:

① Click on this section to link to the appropriate technical paper.
② Click on this section to link to the DirectFET® Website.
③ Surface mounted on 1 in. square Cu board, steady state.
④ T_C measured with thermocouple mounted to top (Drain) of part.
⑤ Repetitive rating; pulse width limited by max. junction temperature.
⑥ Starting $T_J = 25°C$, L = 0.09mH, $R_G = 25\Omega$, $I_{AS} = 74A$.
⑦ Pulse width ≤ 400μs; duty cycle ≤ 2%.
⑧ Used double sided cooling, mounting pad with large heatsink.
⑨ Mounted on minimum footprint full size board with metalized back and with small clip heatsink.
⑩ R_θ is measured at T_J of approximately 90°C.

IMPORTANT NOTICE

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